

TAIEX: 6552

2024/04/23

- * JMC's statements of its current expectations are forward looking statements subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements.
- * Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

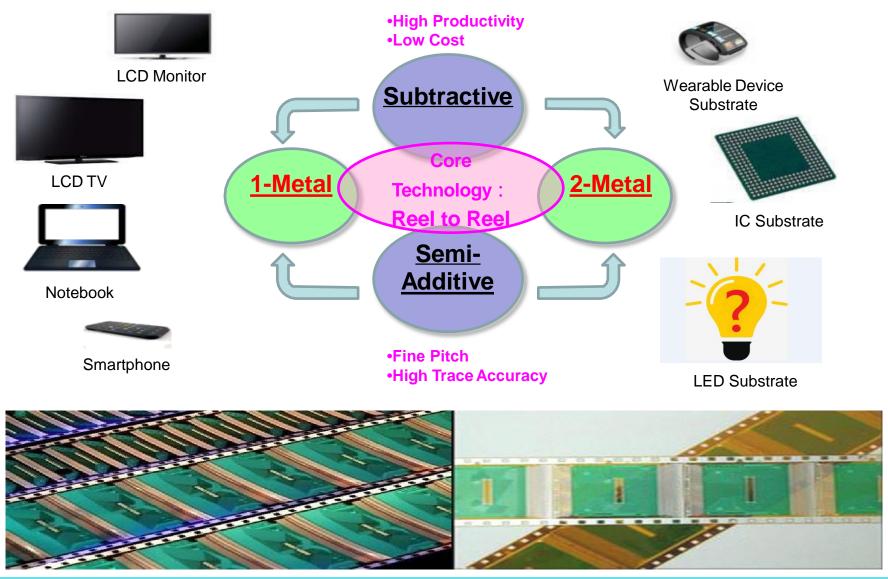


1. Company Introduction - Company Snapshot

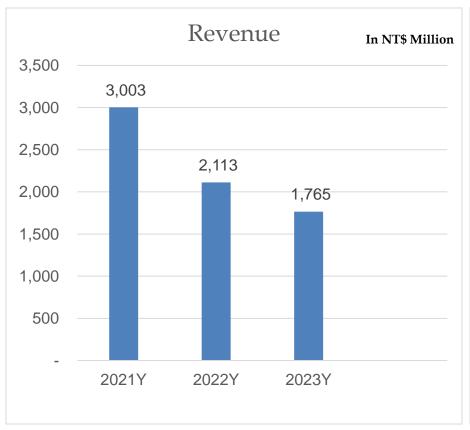
- Established : October 6 ,1973
- Chairman: WAN WEN-TSAI
- General Manager : Jane Lee
- Capital Stock: 830 million
- Major Shareholders: CWE 42.8% \ ChipMos 10%
- Number of employees as of Dec. 31,2023: 622
- Major Product : COF(Reel to Reel Chip on Film)
- Headquarter: Kaohsiung, Taiwan

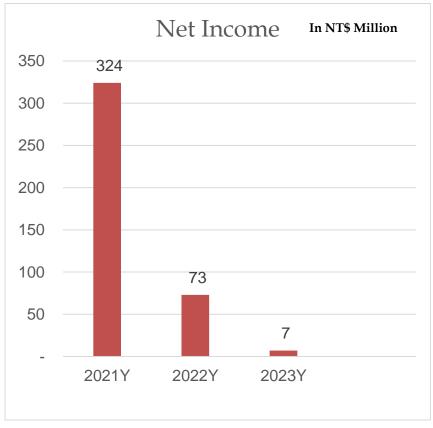


1. Company Introduction - Product Application



2. Financial Results - Results Highlights



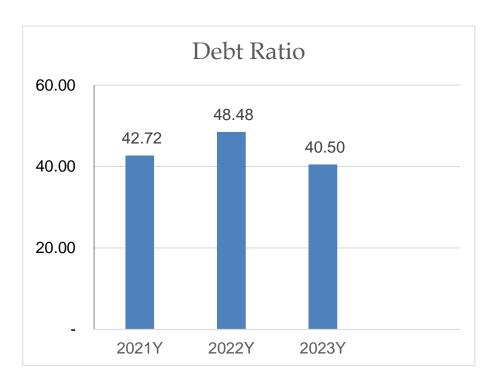


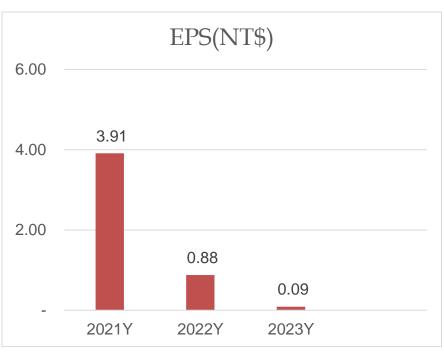
(In NT\$ Million)

Year	2021	2022	2023
Revenue	3,003	2,113	1,765
Net Income	324	73	7



2.Financial Results - Results Highlights



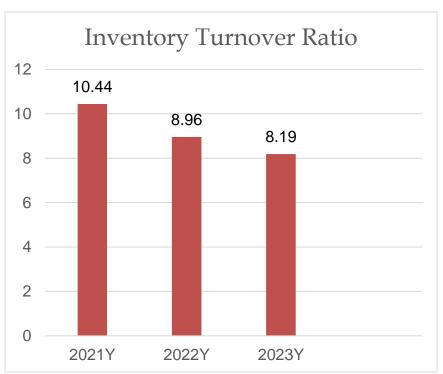


Year	2021	2022	2023
Debt Ratio(%)	42.72	48.48	40.50
EPS(NT\$)	3.91	0.88	0.09



2.Financial Results - Results Highlights





Year	2021	2022	2023
A/R Turnover Ratio	7.62	5.92	6.26
Inventory Turnover Ratio	10.44	8.96	8.19



3.Market & Business Overview – 1 Metal COF for Large Panel

✓ Currently – War, Inflation, and stagnant economy affects global demand

- Global economic growth forecasts continue to be revised downwards.
- War and geographical conflicts continue to increase, causing the uncertainty of the electronic product terminal application market.
- The output value of TV panels and IT panels increased significantly in 2020 and 2021, especially in 2021, reaching The growth rate reached 30% ~40%. However, the highly increased market demand was declined since 2022. In 2023, the panel producers continue to reduce production and destocking.
- It is expected that the panel market will have a chance to return to the traditional demand model in 2024, and further return to a stable demand market in 2025.

✓ Future trend – New design/application, unchanged trend with delayed demand

- TV Panel -4K to 8K, the trend has emerged, just waiting for the demand.
- Monitor/NB/Tablet Panel COG moves to COF due to full-screen/narrow edge design.
- Automotive Panel Starting COF design.



3.Market & Business Overview – 1 Metal COF for Small Panel

✓ <u>Currently – The trend changes on driver IC design of hand-held device.</u>

- Driver IC chips of mobile phone panels: the use of COF design was decreasing due to the increasing in COP design.
- Wearable device with health management functions has become a new trend. Therefore, the COF usage in this field is growing steadily.

✓ Future trend – New design and application with unchanged trend

- High-end smartphone with flexible OLED : COP ↑ / 1-Metal COF ↓.
- Mid-range smartphone with rigid OLED/LTPS: FHD TDDI/FTDDI use 1-Metal COF / partial COG.
- Low-end smartphone with a-Si/LTPS: HD use COG / FHD TDDI use 1-Metal COF.
- Wearable Device: The design turns to 1-Metal COF instead of COG due to the narrow edge requirement. The market is still growing up.



3.Market & Business Overview – 2 Metal Substrate

- ✓ <u>Currently Mini LED direct display and backlight market are moving forward together, applications are well-developed.</u>
 - 2021 can be a year of increase in Mini LED-related products, which accelerated the development of next-generation display technology in 2022. At the CES exhibition in early 2022, all producers published new displays actively, include many Micro LED-related products, which shows the development of the advanced display product market.
 - In 2023, the development and application of Micro LED will become more active.
 - It is expected that 2 Metal Substrate will have the opportunity to apply in Mini/Micro LED products in 2024.
- ✓ Future trend New design and application
 - 2-Metal technology: In addition to the development and application of Mini/Micro LED, JMC will also expand other applications of IC substrate.



3.Market & Business Overview – Technology & Product

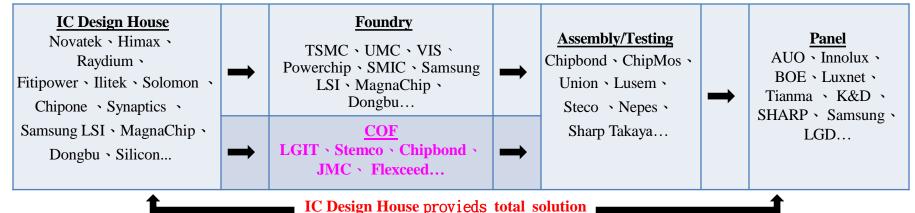
✓ A full service of flexible IC substrate provider

Process Technology	Competitive advantages	Technology/ Application	Targeted Market/ Development
1-Metal Subtractive (Etching)	Fast production and high efficiency.Independent technical ability and stable production yield.	*Copper thickness #~8um *Pitch >=20um Pitch *Pin count =<1440 Channel/48mm	@ LCD TV @ OLED TV @ Dual Cell LCD
1-Metal Semi- Additive (Plating)	 ©High precision size controlled COF products, and can improve the assembly of the panel module rate; help customers to lower total cost. ©High production yield and good quality stability; absolute competitive advantage in production costs. 	*Copper thickness #~12um *Pitch >=18/16/14um Pitch *Pin count =<1900 Channel/48mm =<3000 Channel/70mm	 @ High-end smartphone @ wearable device @ FoD @ FTDDI
©New process technology development capabilities. ©Equipment design capability. ©Good cost control.		*Thin Film IC Substrate *LED IC Substrate *Pin count =<2500 Channel/48mm =<4000 Channel/70mm	@ LCD @ Mini LED @ Micro LED @ IC Substrate



4.Industry Outlook - Driver IC Supply Chain

IC Design House provides total solution.



Five COF suppliers have mass production capacity currently, and JMC is just one of the two vendors in Taiwan.

Proc	cess Techno	logy	1-Metal Subtractive(Etching)	1-Metal Semi-Additive(Plating)	2-Metal
Channel/48mm		el/48mm	=<1400 /48mm	1400~1900 /48mm	1900~2500 /48mm
Application	Channel/70mm		=<2000 /70mm	2000~3000 /70mm	3000~4000 /70mm
		S社	90~100KK	?KK(2-Metal→1-Metal)	7-10KK
Capacity	Korea	L社	120~130KK	?KK(2-Metal→1-Metal)	5-7KK
	Japan	F社	20KK	Х	2KK
		C社	70~90KK	Х	Х
	Taiwan	JMC	40KK	40KK	5KK
	China	ESWIN Aplus	?	? ?	?



Q&A

